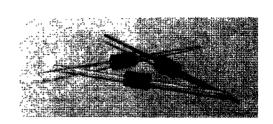
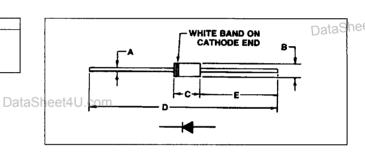


# 3 Amp Schottky Rectifiers 150°C MAX T,

20 Volt, 30 Volt and 40 Volt  $V_{\text{RRM}}$  .475 Volt  $V_{\text{F}}$  at  $I_{\text{F}}=3.0$  Amps Very Fast Switching Speed Minimum Sized, Low Cost Epoxy Encapsulation



LTR.	INCHES	MILLIMETERS
A	.048052 Dia.	1,22-1,32 Dia.
l B l	.190225	4,83–5,72
	.36–.37	9,14–9,40
D	2.6–2.8	66,0-71,1
l E I	1.137-1.237	28,33-31,42



MAYIMIM PATINGS (At T. - 25°C unless otherwise noted)

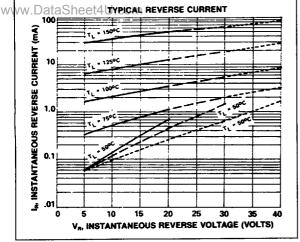
RATINGS	SYMBOL V <sub>RM</sub> V <sub>RWM</sub> V <sub>RRM</sub>	<b>VSK320</b> 20	<b>VSK330</b>	<b>VSK340</b> 40	Volts
DC Blocking Voltage Working Peak Reverse Voltage Peak Repetitive Reverse Voltage					
RMS Reverse Voltage	V <sub>R(RMS)</sub>	14	21	28	Volts
Average Rectified Forward Current (Fig. 5 & 6)	10	3.0		Amps	
Ambient Temp. @ Rated V <sub>RM</sub> , R <sub>BJA</sub> ≤ 24°C/W	T <sub>A</sub>	85	80	75	°C
Peak Surge Current (non-rep), 300µs Pulse Width (Fig. 4)	I <sub>FSM</sub>	250		Amps	
Peak Surge Current (non-rep), ½ cycle, 60Hz (Fig. 4)	I <sub>FSM</sub>	150		Amps	
Operating Junction Temperature	T₃	- 65 to + 150*		°C	
Storage Temperature	Тета	Tere - 65 to + 150			•c

<sup>\*</sup>  $V_{RM} \le 0.1 V_{RM} Max$ ,  $R_{6JA} \le 32^{\circ}C/W$ 

ELECTRICAL CHARACTERISTICS (At T<sub>A</sub> = 25°C unless otherwise noted)

ı	CHARACTERISTICS		SYMBOL	VSK320	VSK330	VSK340	UNITS
	Maximum Instantaneous Forward Voltage Drop (1) See Fig. 2 for Typical V <sub>F</sub>	$I_F = 1.0 \text{ Amp}$ $I_F = 3.0 \text{ Amps}$ $I_F = 10.0 \text{ Amps}$	V <sub>F</sub>		.400 .475 .750	www.DataS	neet4U.co Volts
ı	Maximum Instantaneous Reverse Current at Rated V <sub>PM</sub> (1) See Fig. 1 for Typical I <sub>R</sub>	T <sub>J</sub> = 25°C T <sub>J</sub> = 100°C	i <sub>R</sub>		3.0 30.0		mA

<sup>(1)</sup> Pulse Test: Pulse Width = 300 μs, Duty Cycle = 2%



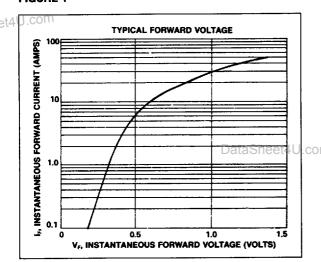
# T-03-1

 VSK330 VSK340

VSK320

PULSE WIDTH - 300 µsec  $T_L = LEAD TEMP. MEASURED .03" FROM$ RECTIFIER BODY WITH 40 GAUGE THERMOCOUPLE

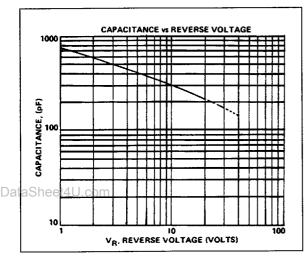
#### FIGURE 1



DataShe

PULSE WIDTH = 300 µsec  $T_A = 25^{\circ}C$ 

## FIGURE 2



VSK330 VSK340  $T_A = 25^{\circ}C$ 

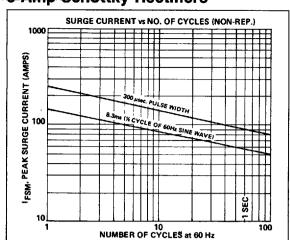
VSK320

TEST FREQ. = 100 kHz

The current flow in Schottky barner rectifier is due to majority carrier conduction and is not affected by reverse recovery transients due to stored charge and minority carrier injection as in conventional PN

The Schottky barrier rectifier may be considered for COM purposes of circuit analysis, as an ideal diode in parallel with a variable capacitance equal in value to the junction capacitance. See Figure 3.

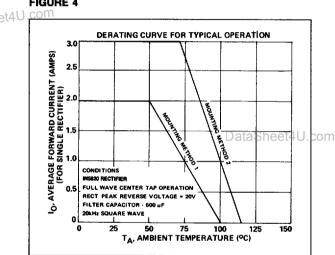
# www3DAmp Schottky Rectifiers



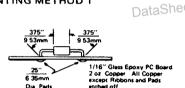
## T-03-15

 $T_A = 25^{\circ}C$ 

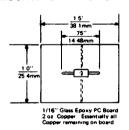
#### FIGURE 4



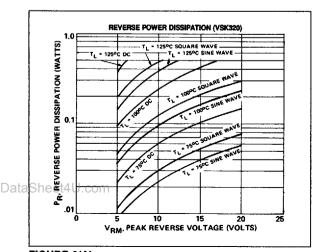
#### **MOUNTING METHOD 1**

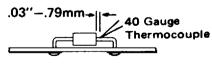


#### MOUNTING METHOD 2 - TOP VIEW



### FIGURE 5



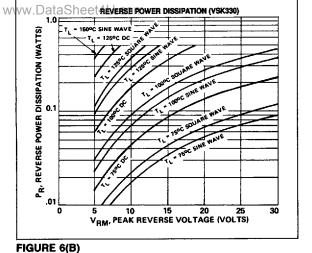


REVERSE POWER MULTIPLIES 1 32x FOR EACH 5°C TEMP. INCREASE.

USE THIS MULTIPLIER FOR INTERPOLATION BETWEEN CURVES SHOWN ON FIGURES 6(A), 6(B), 6(C).

USE 75°C CURVES/FOR ALL SASSheet 4U.com TEMP. BELOW 75°C

FIGURE 6(A) COM



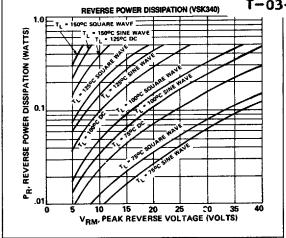
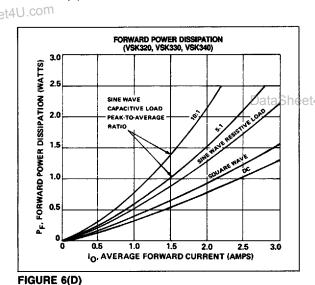


FIGURE 6(C)



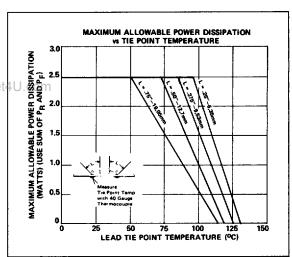


FIGURE 6(E)

lead.

#### Thermal Considerations:

- 1. The derating curve of figure 5 may be used for initial design work.
- Use the curves of figure 6 to study the voltage / current / temperature parameters. These curves are helpful in determining the rectifier capability when connected to a tie point whose temperature is influenced by other heat producing components. To use these curves, add the reverse power dissipation from figure 6 (A), (B) or (C) to the forward power dissipation from figure
  - temperature.

    3. The heat sink (tie point) must be designed to keep the temperature at this point below that shown on the figure 6 (E) curve. Thermal runaway is entirely possible on marginal designs due to the inherently large reverse leakage of Schottky barrier rectifiers and the fact that reverse power multiplies about 1.32 times for

6 (D). Then go to figure 6 (E) to find the maximum allowable tie point

- The curves of figure 6 (E) were based on full rated reverse bias voltage. Slightly higher tie point temperatures can be tolerated at lower voltages. We recom-
- mend that all designs be verified at an ambient temperature at least 10°C higher than the maximum at which the equipment will ever have to operate.

  i. If the application is such that DC reverse bias is applied that IV 100% of the
- If the application is such that DC reverse bias is applied mady, 100% of the time, all temperature points on curve 6 (E) should be reduced 13 C.
- 6. These thermal resistances apply: R<sub>but</sub>(measured '92" from epoxy) = 6°C/W and the lead = 25°C/W per inch when equal heatsinking is applied to each

each 5°C of temperature increase.